AMENDMENT

Please amend the application as indicated hereafter.

In the Claims :

1. (original) An auto-recovery wafer testing method, comprising:

a first testing step to test sequentially a plurality of chips on a wafer and spontaneously save testing data for each of the chips;

an auto-recovery data generating step, wherein, if the first testing step is accidentally interrupted, auto-recovery data are generated based on the testing data that is saved; and

a second testing step for continuing the testing, based on the auto-recovery data, from a chip being last but incompletely tested.

2. (original) The wafer testing method as recited in claim 1, wherein, during the first testing step, a first testing unit is used to test the chips and output corresponding testing data for each of the chips.

3. (original) The wafer testing method as recited in claim 1, wherein, during the first testing step, a real-time accessing module is used to instantaneously save testing data for each of the chips.

4. (original) The wafer testing method as recited in claim 1, further comprising a problem-eliminating step, after the auto-recovery data generating step and before the second testing step, so as to ensure the first testing unit operating properly.

5. (original) The wafer testing method as recited in claim 4, wherein, during the

2

second testing step, the first testing unit is used for continuing the testing, based on the auto-recovery data, from a chip being last but incompletely tested.

6. (original) The wafer testing method as recited in claim 1, further comprising a transfer step, after the auto-recovery data generating step and before the second testing step, so as to transfer the wafer from the first testing unit to a second testing unit.

7. (original) The wafer testing method as recited in claim 6, during the second testing step, the second testing unit is used for continuing the testing, based on the auto-recovery data, from a chip being last but incompletely tested.

8.-11. (canceled)

3